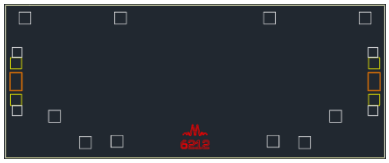
Passive MMIC 26-40GHz Bandpass Filter MFB-3300

The MFB-3300 is a passive MMIC bandpass filter. It is a low loss integrated filter that passes the Ka (26-40GHz) band. Passive GaAs MMIC technology allows production of smaller filter constructions that replace larger form factor circuit board constructions. Tight fabrication tolerances allow for less unit to unit variation than traditional filter technologies. The MFB-3300 is available as a wire bondable chip. Low unit to unit variation allow for accurate simulations using the provided S2P file taken from measured production units.



Features

- Designed for Ka Band
- Insertion Loss Typically 1.5dB at Center Frequency
- Excellent Return Loss
- High Stop Band Suppression
- Wide Stop Band
- Connectorized module available late 2017
- MFB-3300.S2P

Electrical Specifications - Specifications guaranteed +25°C for chip (CH) package, measured in a 50Ω system.

Parameter	Frequency (GHz)	Min	Typ.	Max
Center Frequency, f_c (GHz)	33			
Passband (GHz)	26-40			
Insertion Loss @ f_c (dB)			1.5	3
Passband Return Loss (dB)	26-40		15	
Stopband Suppression (dB)	11.1, 50 18.7, 44.8	40 25	50 30	
Impedance (Ω)			50	

Part Number Options

Please specify package style by adding to model number.			
Package Styles		**Examples**	
Connectorized[1, 3-4]	Available Late 2017	MFB-3300CH	
Chip[1-2] (RoHS)	CH	MFB-3300 (Model)	CH (Package)

[1]Chip package connects to external circuit through wire bondable gold pads.
[2]Note: For port locations and I/O designations, refer to the drawings on page 2 of this document.

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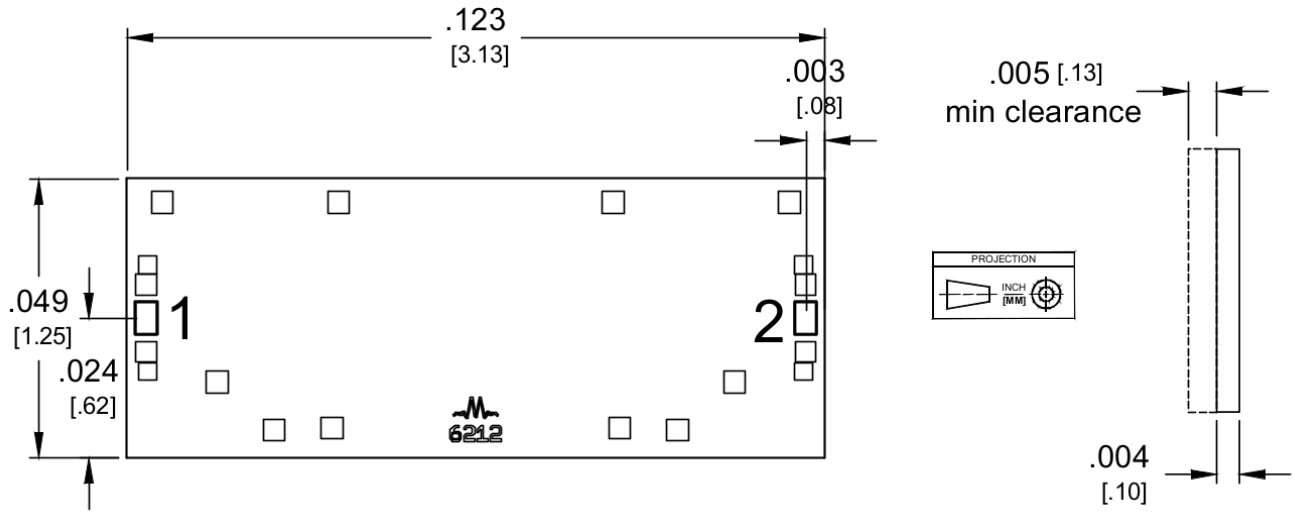

1. CH Substrate material is .004 thick GaAs.
2. I/O traces finish is 5 microns Au. Ground plane finish is 4 microns Au.
3. Wire Bonding - Ball or wedge bond with 0.025 mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible <0.31 mm (12 mils).

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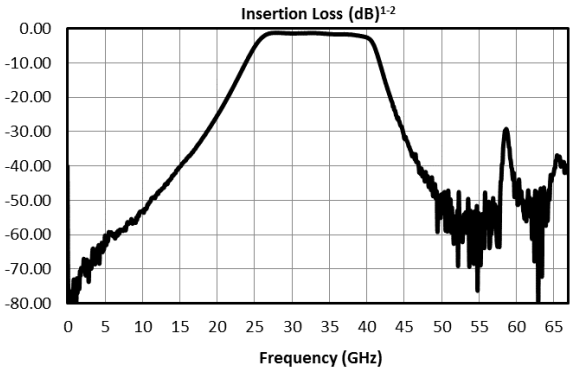
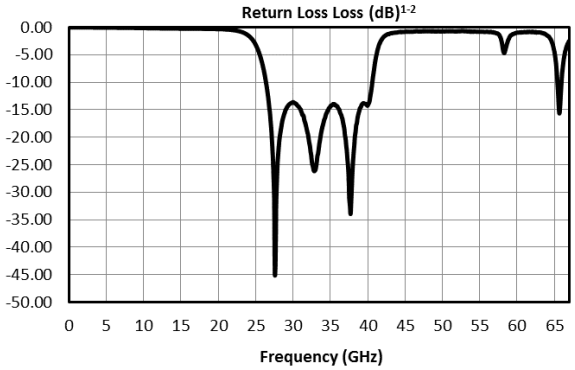
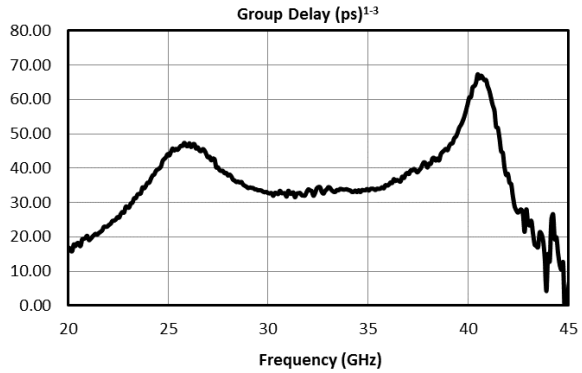
Typical Performance







Mounting and Bonding Recommendations

Marki MMICs should be attached directly to a ground plane with conductive epoxy. The ground plane electrical impedance should be as low as practically possible. This will prevent resonances and permit the best possible electrical performance. Datasheet performance is only guaranteed in an environment with a low electrical impedance ground.

Mounting - To epoxy the chip, apply a minimum amount of conductive epoxy to the mounting surface so that a thin epoxy fillet is observed around the perimeter of the chip. Cure epoxy according to manufacturer instructions.

Wire Bonding - Ball or wedge bond with 0.025 mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible <0.31 mm (12 mils).

Circuit Considerations – 50 Ω transmission lines should be used for all high frequency connections in and out of the chip. Wirebonds should be kept as short as possible, with multiple wirebonds recommended for higher frequency connections to reduce parasitic inductance. In circumstances where the chip more than .001" thinner than the substrate, a heat spreading spacer tab is optional to further reduce bondwire length and parasitic inductance.

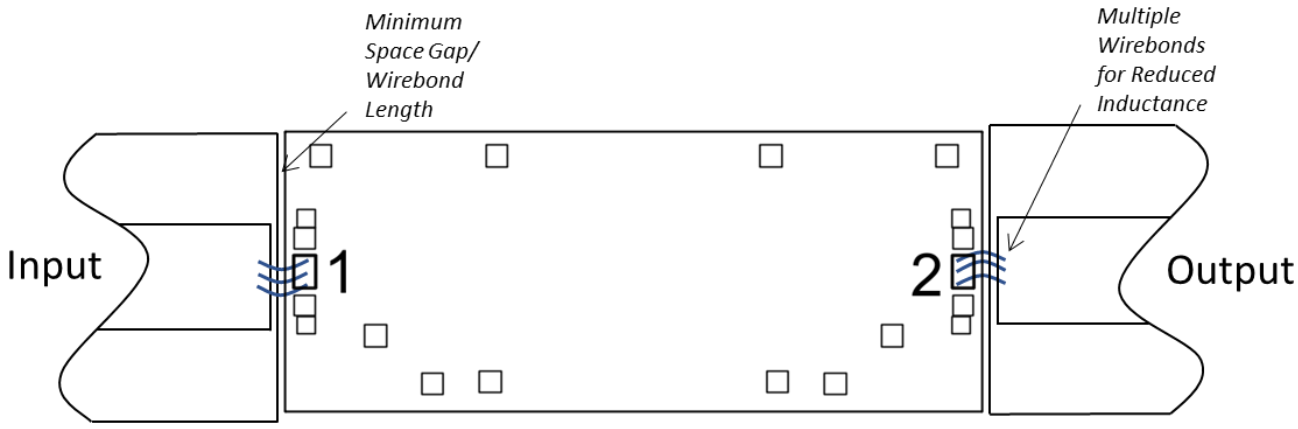
Handling Precautions

General Handling: Chips should be handled with a vacuum collet when possible, or with sharp tweezers using well trained personnel. The surface of the chip is fragile and should not be contacted if possible.

Static Sensitivity: GaAs MMIC devices are subject to static discharge, and should be handled, assembled, tested, and transported only in static protected environments.

Cleaning and Storage: Do not attempt to clean the chip with a liquid cleaning system or expose the bare chips to liquid. Once the ESD sensitive bags the chips are stored in are opened, chips should be stored in a dry nitrogen atmosphere.

Bonding Diagram



Absolute Maximum Ratings	
Parameter	**Maximum Rating**
Port 1 DC Current	N/A
Port 2 DC Current	N/A
RF Power Handling	+30 dBm
Spec Guaranteed Operating Temperature	+25°C
Survivable Operating Temperature	-65ºC to +125ºC
Storage Temperature	-65ºC to +125ºC

DATA SHEET NOTES:
1. Filter is symmetrical. Reverse measurement is equivalent to forward measurement.
2. Measured typical data available for integrated circuit only. Connectorized data available when released.
3. Group delay calculated using wrapped phase response.
4. Specifications are subject to change without notice. Contact Marki Microwave for the most recent specifications and data sheets.
5. Catalog circuits are continually improved. Configuration control requires custom model numbers and specifications

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Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.